

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT4211491

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YOSHIHIRO TOMITA	01/27/2016
BASSAM M ZIADEH	10/25/2016
NITIN DESHPANDE	01/05/2017
OMKAR KARHADE	01/27/2016
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	INTEL CORPORATION
<b>Street Address:</b>	2200 MISSION COLLEGE BLVD.
<b>City:</b>	SANTA CLARA
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95054
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14974811
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	612-373-6900
<b>Email:</b>	request@slwip.com
<b>Correspondent Name:</b>	SCHWEGMAN, LUNDBERG & WOESSNER/INTEL
<b>Address Line 1:</b>	C/O CPA GLOBAL
<b>Address Line 2:</b>	900 SECOND AVENUE SOUTH SUITE 600
<b>Address Line 4:</b>	MINNEAPOLIS, MINNESOTA 55402
<b>ATTORNEY DOCKET NUMBER:</b>	884.T51US1
<b>NAME OF SUBMITTER:</b>	NANCY CUNDALL
<b>SIGNATURE:</b>	/Nancy Cundall/
<b>DATE SIGNED:</b>	01/05/2017
<b>Total Attachments: 9</b>	
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RECORDATION FORM COVER SHEET  
PATENTS ONLY

Atty Ref/Docket No.: 884.T51US1

Patent and Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Yoshihiro Tomita, Bassam M. Ziadeh, Nitin Deshpande,  
Omkar Karhade

Additional name(s) of conveying party(ies) attached?

Yes  No

3. Nature of conveyance:

Assignment  Merger  
 Security Agreement  Change of Name  
 Other

Execution Date: January 27, 2016, October 25, 2016,  
January 5, 2017, January 27, 2016

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95054  
Country: United States of America

Additional name(s) & address(es) attached?  Yes  No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

Serial No. 14/974,811

B. Patent No.(s)

Additional numbers attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Andrew R. Peret

Address:

Schwegman Lundberg & Woessner, P.A.  
P.O. Box 2938  
Minneapolis, MN 55402--0938

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 0.00

Enclosed

Authorized to be charged to deposit account  
504238

8. Please charge any additional fees or credit any over payments to our Deposit Account No.: 504238

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Andrew R. Peret/Reg. No. 41,246

Name of Person Signing

1 Andrew Peret 1

Signature

January 5, 2017

Date

Total number of pages including cover sheet: 9

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks  
Mail Stop Assignment Recordation Services  
P.O. Box 1450  
Alexandria, VA 22313-1450

PATENT  
REEL: 040859 FRAME: 0934

## ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

**<Omkar Karhade, Nitin Deshpande, Bassam M. Zlodeh, Yoshihiro Tomita>**

herby sell, assign, and transfer to:

### **Intel Corporation**

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

### **INTEGRATED CIRCUIT ASSEMBLY THAT INCLUDES STACKED DICE**

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on December 18, 2015 as

United States of America Application Number 14/974,811

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors, assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and

the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title in said inventions and improvements, and all applications for patents and all patents on said improvements. In said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

*Yoshihiro Tomita*

Yoshihiro Tomita

*1/27/2016*

Date Signed

Bassem M. Ziadeh

Date Signed

Nitin Deshpande

Date Signed

Omkar Karhade

Date Signed

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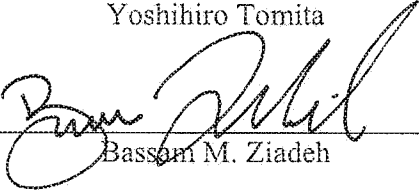
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covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

\_\_\_\_\_  
Yoshihiro Tomita  
  
\_\_\_\_\_  
Bassam M. Ziadeh

\_\_\_\_\_  
Date Signed  
  
10/25/10  
\_\_\_\_\_  
Date Signed

\_\_\_\_\_  
Nitin Deshpande

\_\_\_\_\_  
Date Signed

\_\_\_\_\_  
Omkar Karhade

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Date Signed

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Nitin Deshpande

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Date Signed

  
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Omkar Karhade

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V27/16  
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Date Signed